



## Material Content Data Sheet



<b>Sales Product Name</b>		SPW52N50C3		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000364066						
<b>Package</b>		PG-TO247-3-41		<b>Weight*</b>		6059.71 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	35.052	0.58	0.58	5784	5784
leadframe	non noble metal	iron	7439-89-6	3.972	0.07		656	
	inorganic material	phosphorus	7723-14-0	1.192	0.02		197	
	non noble metal	copper	7440-50-8	3967.074	65.46	65.55	654663	655516
wire	non noble metal	aluminium	7429-90-5	9.506	0.16	0.16	1569	1569
encapsulation	organic material	carbon black	1333-86-4	19.696	0.32		3250	
	plastics	epoxy resin	-	374.226	6.18		61757	
	inorganic material	silicondioxide	60676-86-0	1575.690	26.00	32.50	260028	325035
leadfinish	non noble metal	tin	7440-31-5	31.874	0.53	0.53	5260	5260
plating	non noble metal	nickel	7440-02-0	29.065	0.48	0.48	4796	4796
solder	non noble metal	antimony	7440-36-0	1.236	0.02		204	
	noble metal	silver	7440-22-4	3.091	0.05		510	
	non noble metal	tin	7440-31-5	8.036	0.13	0.20	1326	2040
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com